May 13, 2009

Customer Notification
Change to waffle pack used for die sales product

Dear Valued Customer:

This notification is to inform you of a change to the waffle pack tray for product sold in die form. This change is to migrate to a slightly larger die pocket dimension as shown in Table 1 below.

**Purpose**
The purpose is to create better uniformity in trays supplied to customers that purchase trayed die.

**Old Tray** – H20-045-66C02
**New Tray** – H20-050-16-66C02

**Product Affected**

| M02006-WP-T | M02006E-WP-T | M02007-3-WP-T |
| M02011-11   | M02013-3A    | M02014-11     |
| M02015-11   | M02016-3A    | M02020-12     |
| M02024-12   | M02026-12    |               |

**Change Schedule**
Migration to the new packing tray will be phased in as follows:

1) **M02011-11**
   Migration to new trays on Product Date Coded 0920 onwards.
2) **All other codes (with exception of M02016-3A)**
   Migration to new trays on Product Date Coded 0921 onwards.
3) **M02016-3A**
   Product will continue to ship in the current tray and will migrate to new trays upon depletion of old tray stock.

**Method to identify parts**
Trays have the part number molded on the upper right hand edge when the tray is oriented with chamfer in upper left corner.

**Customer Impact**
No customer impact is anticipated with this change; there is no change to form, fit, or function of devices. The outside dimensions of the tray will remain the same as well as the die count per tray.

<table>
<thead>
<tr>
<th></th>
<th>Outside Tray Dimension</th>
<th>Die pocket Dimension</th>
<th>Die Ct. per Tray</th>
</tr>
</thead>
<tbody>
<tr>
<td>Old</td>
<td>2” x 2”</td>
<td>0.045” x 0.045” x 0.011”</td>
<td>20 x 20 (400)</td>
</tr>
<tr>
<td>New</td>
<td>2” x 2”</td>
<td>0.050” x 0.050” x 0.016”</td>
<td>20 x 20 (400)</td>
</tr>
</tbody>
</table>

We are confident this change will allow Mindspeed Technologies to maintain its high standards for quality and reliability. We will be managing this change very closely to ensure minimum disruption to our customers. If, at any time, you have a need for further information, please contact your local Sales Representative.
May 13, 2009

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The indicated Customer Notification letter was received and acknowledged by the undersigned authority.

Name: ________________________________
Signature: ________________________________
Print: ________________________________

Company: ________________________________
Name: ________________________________
Location: ________________________________

Title: ________________________________

Date: ________________________________

Comments/additional requests: __________________________________________

Thank you for your attention on this matter.

Please return the acknowledgment form to the attention of Tom Towey at Mindspeed Technologies Inc., 4000 MacArthur Blvd, Newport Beach, Ca, 92660; thomas.towey@mindspeed.com.